

HIGH VOLTAGE $I_o = 500$ mA ADJUSTABLE LDO REGULATOR

■ FEATURES*

- AEC-Q100 grade 1 qualified
- Fast transient response
- Wide operating voltage 4.0 V to 40 V
- Wide operating temperature $T_a = -40^{\circ}\text{C}$ to 125°C
- High-accuracy ADJ voltage
 - $V_{ADJ} = 1.24\text{ V} \pm 1.0\%$ ($T_a = 25^{\circ}\text{C}$)
 - $V_{ADJ} = 1.24\text{ V} \pm 2.0\%$ ($T_a = -40^{\circ}\text{C}$ to 125°C)
- Adjustable output voltage range 2.5 V to 16 V
- Output current 500 mA (min)
- ON/OFF control
- Ceramic capacitor compatible
- Undervoltage lockout
- Thermal shutdown
- Overcurrent protection
- Package TO-252-5-L5

■ APPLICATIONS*

- Car infotainment
- Automotive ECUs
- Industrial equipment

*T1 grade is not recommended for powertrain, vehicle electrification and autonomous driving related applications.

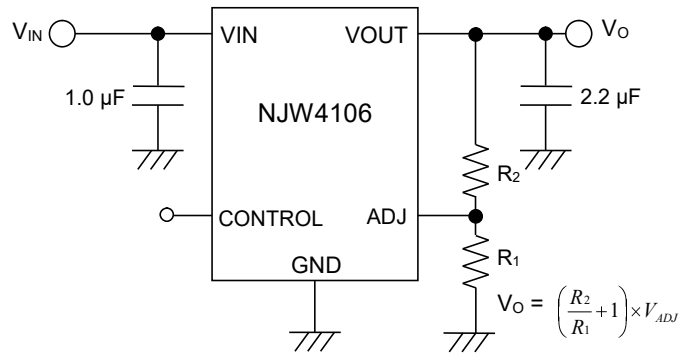
■ DESCRIPTION

The NJW4106-T1 is a 45 V, $I_o = 500$ mA fast transient response low dropout regulator. This device achieves fast transient response and offers stable output voltage at line or load fluctuations.

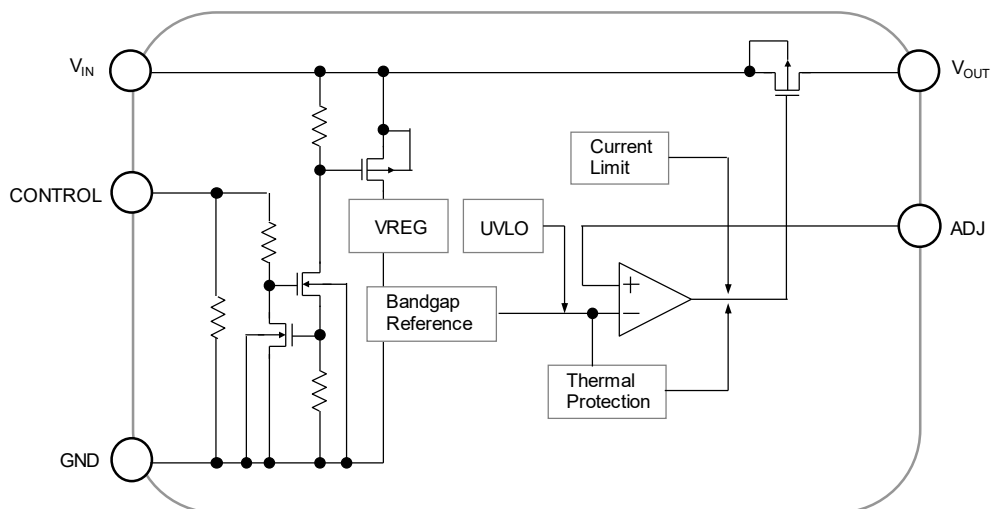
The NJW4106-T1 provides outstanding high ADJ voltage accuracy that guaranteed $1.24\text{ V} \pm 2.0\%$ under the conditions of $V_{IN} = V_o + 1\text{ V}$ to 40 V, $I_o = 0$ mA to 500 mA, and $T_a = -40^{\circ}\text{C}$ to 125°C .

Moreover, wide operating voltage and wide operating temperature makes the NJW4106-T1 ideal for automotive equipment or applications that require high reliability.

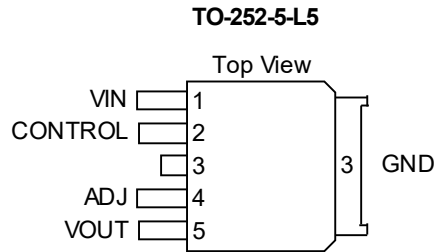
■ TYPICAL APPLICATION



■ BLOCK DIAGRAM

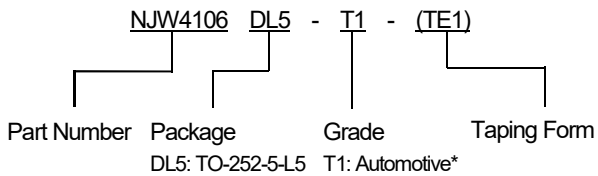


■ PIN CONFIGURATION



| PIN NO. | NAME | FUNCTION |
|---------|---------|-------------------------------|
| 1 | VIN | Input pin |
| 2 | CONTROL | ON/OFF control pin |
| 3 | GND | Ground pin |
| 4 | ADJ | Output voltage adjustment pin |
| 5 | VOUT | Output pin |

■ PRODUCT NAME INFORMATION



* The detail information of automotive grades and recommended applications are described in NJR website.
 (https://www.njr.com/electronic_device/semiconductor/application/automotive.html.)

■ ORDERING INFORMATION

| PRODUCT NAME | PACKAGE | RoHS | HALOGEN-FREE | TERMINAL FINISH | MARKING | WEIGHT (mg) | MOQ (pcs) |
|---------------------|-------------|------|--------------|-----------------|---------|-------------|-----------|
| NJW4106DL5-T1 (TE1) | TO-252-5-L5 | Yes | Yes | Sn-2Bi | 4106T1 | 301 | 3000 |

■ ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | RATING | UNIT |
|---|------------|--|------------------|
| Input Voltage | V_{IN} | -0.3 to 45 | V |
| Control Pin Voltage | V_{CONT} | -0.3 to 45 | V |
| ADJ Pin Voltage | V_{ADJ} | -0.3 to 6 | V |
| Output Voltage | V_O | -0.3 to $V_{IN} \leq +17$ ⁽¹⁾ | V |
| Power Dissipation ($T_a = 25^\circ\text{C}$) TO-252-5-L5 | P_D | 2-Layer / 4-Layer / High Power 4-Layer 870 ⁽²⁾ / 3000 ⁽³⁾ / 4700 ⁽⁴⁾ | mW |
| Junction Temperature | T_j | -40 to 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{stg} | -50 to 150 | $^\circ\text{C}$ |

(1) When the input voltage is less than 17 V, the absolute maximum output voltage is equal to the input voltage. If the input voltage is below 17 V, the maximum output voltage is 17 V.

(2) 2-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 2-layer FR-4).

(3) 4-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 4-layer FR-4).
(For 4-layer: Applying 74.2 mm × 74.2 mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5.)

(4) High Power 4-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm, 4-layer FR-4).

(For 4-layer: Applying 74.2 mm × 74.2 mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5.)

*For the specifications of each board, see the Board Specifications of THERMAL CHARACTERISTICS.

■ RECOMMENDED OPERATING CONDITIONS

| PARAMETER | SYMBOL | VALUE | UNIT |
|---------------------------------|------------|------------|------------------|
| Operating Voltage | V_{IN} | 4.0 to 40 | V |
| Control Voltage | V_{CONT} | 0 to 40 | V |
| Output Voltage Setting | V_O | 2.5 to 16 | V |
| Output Voltage Setting Resistor | R_1 | 5 to 500 | k Ω |
| Output Current | I_O | 0 to 500 | mA |
| Operating Temperature | T_{opr} | -40 to 125 | $^\circ\text{C}$ |

■ ELECTRICAL CHARACTERISTICS

$V_O \geq 3\text{ V}$: $V_{IN} = V_O + 1\text{ V}$, $C_{IN} = 1.0\ \mu\text{F}$, $C_O = 2.2\ \mu\text{F}$, $R_1 = 250\ \text{k}\Omega$, $T_a = 25^\circ\text{C}$

$V_O < 3\text{ V}$: $V_{IN} = 4.0\text{ V}$, $C_{IN} = 1.0\ \mu\text{F}$, $C_O = 4.7\ \mu\text{F}$, $R_1 = 250\ \text{k}\Omega$, $T_a = 25^\circ\text{C}$, unless otherwise noted.

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|------------------------------|--|-------|----------|-------|-----------------------|
| ADJ Voltage | V_{ADJ} | $V_{IN} = 4\text{ V to } 40\text{ V}$ ($V_O < 3\text{ V}$), $V_{IN} = V_O + 1\text{ V to } 40\text{ V}$ ($V_O \geq 3\text{ V}$), $I_O = 0\text{ mA to } 500\text{ mA}$ | -1.0% | 1.24 | +1.0% | V |
| | | $V_{IN} = 4\text{ V to } 40\text{ V}$ ($V_O < 3\text{ V}$), $V_{IN} = V_O + 1\text{ V to } 40\text{ V}$ ($V_O \geq 3\text{ V}$), $I_O = 0\text{ mA to } 500\text{ mA}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | -2.0% | - | +2.0% | |
| Quiescent Current | I_Q | $I_O = 0\text{ mA}$, except I_{CONT} | - | 65 | 105 | μA |
| | | $I_O = 0\text{ mA}$, except I_{CONT} , $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 115 | |
| Quiescent Current at Control OFF | $I_{Q(OFF)}$ | $V_{CONT} = 0\text{ V}$ | - | - | 1 | μA |
| | | $V_{CONT} = 0\text{ V}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 1 | |
| Output Current | I_O | $V_O \times 0.9$ | 500 | - | - | mA |
| | | $V_O \times 0.9$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | 500 | - | - | |
| Line Regulation | $\Delta V_O / \Delta V_{IN}$ | $V_{IN} = V_O + 1\text{ V to } 40\text{ V}$, $I_O = 30\text{ mA}$, $V_O = 5.0\text{ V}$ | - | - | 34.0 | mV |
| | | $V_{IN} = V_O + 1\text{ V to } 40\text{ V}$, $I_O = 30\text{ mA}$, $V_O = 5.0\text{ V}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 51.0 | |
| Load Regulation | $\Delta V_O / \Delta I_O$ | $I_O = 0\text{ mA to } 500\text{ mA}$, $V_O = 5.0\text{ V}$ | - | - | 22.5 | mV |
| | | $I_O = 0\text{ mA to } 500\text{ mA}$, $V_O = 5.0\text{ V}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 45.0 | |
| Ripple Rejection | RR | $V_{IN} = V_O + 1\text{ V}$, $e_{in} = 200\text{ mVrms}$, $f = 1\text{ kHz}$, $I_O = 30\text{ mA}$, $V_O = 5.0\text{ V}$ | - | 53 | - | dB |
| Dropout Voltage 1 | ΔV_{IO1} | $I_O = 300\text{ mA}$ | - | 0.24 | 0.42 | V |
| | | $I_O = 300\text{ mA}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 0.60 | |
| Dropout Voltage 2 | ΔV_{IO2} | $I_O = 500\text{ mA}$ | - | 0.40 | 0.70 | V |
| | | $I_O = 500\text{ mA}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 1.00 | |
| Control Current | I_{CONT} | $V_{CONT} = 1.6\text{ V}$ | - | 0.5 | 2.0 | μA |
| | | $V_{CONT} = 1.8\text{ V}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 3.0 | |
| Control Voltage for ON-State | $V_{CONT(ON)}$ | | 1.6 | - | - | V |
| | | $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | 1.8 | - | - | |
| Control Voltage for OFF-State | $V_{CONT(OFF)}$ | | - | - | 0.6 | V |
| | | $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | - | - | 0.6 | |
| UVLO Release Voltage | V_{UVLO} | $V_{IN} = \text{low to high}$ | 2.3 | 2.7 | 3.1 | V |
| | | $V_{IN} = \text{low to high}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | 2.2 | - | 3.2 | |
| UVLO Hysteresis Voltage | V_{HYS} | $V_{IN} = \text{high to low}$ | 200 | 500 | - | mV |
| | | $V_{IN} = \text{high to low}$, $T_a = -40^\circ\text{C to } 125^\circ\text{C}$ | 200 | - | - | |
| Average Temperature Coefficient of Output Voltage | $\Delta V_O / \Delta T_a$ | $T_a = -40^\circ\text{C to } 125^\circ\text{C}$, $I_O = 30\text{ mA}$ | - | ± 50 | - | ppm/ $^\circ\text{C}$ |

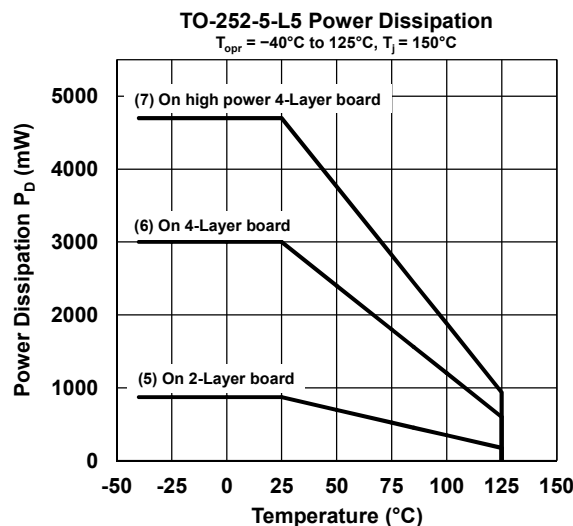
■ THERMAL CHARACTERISTICS

| PARAMETER | SYMBOL | VALUE | UNIT |
|--|---------------|--|------|
| Junction-To-Ambient Thermal Resistance TO-252-5-L5 | θ_{ja} | 2-Layer / 4-Layer / High Power 4-Layer 143 ⁽⁵⁾ / 41 ⁽⁶⁾ / 26 ⁽⁷⁾ | °CW |
| Junction-To-Top of Package Characterization Parameter TO-252-5-L5 | ψ_{jt} | 2-Layer / 4-Layer / High Power 4-Layer 30 ⁽⁵⁾ / 15 ⁽⁶⁾ / 11 ⁽⁷⁾ | °CW |

■ BOARD SPECIFICATIONS

| BOARD | | JEDEC 2-LAYER BOARD | JEDEC 4-LAYER BOARD | HIGH POWER 4-LAYER BOARD |
|--------------|---|---|--|---|
| Dimension | | 76.2 mm × 114.3 mm, t = 1.6 mm | | |
| Material | | FR-4 | | |
| Cu Area | Surface Layer (Thickness: 70 μm) | NJR recommended land pattern + Measurement wiring | NJR recommended land pattern + Measurement wiring | NJR recommended land pattern + Heat dissipation pattern (50 mm × 50 mm) + Measurement wiring |
| | 2 nd Layer (Thickness: 35 μm) | - | 74.2 mm × 74.2 mm | 74.2 mm × 74.2 mm |
| | 3 rd Layer (Thickness: 35 μm) | - | 74.2 mm × 74.2 mm | 74.2 mm × 74.2 mm |
| | Back Layer (Thickness: 70 μm) | - | - | 74.2 mm × 74.2 mm |
| Thermal Vias | | - | Connected from surface layer to 2 nd layer | All layers are connected |

■ POWER DISSIPATION vs. AMBIENT TEMPERATURE



(5) 2-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 2-layer FR-4).

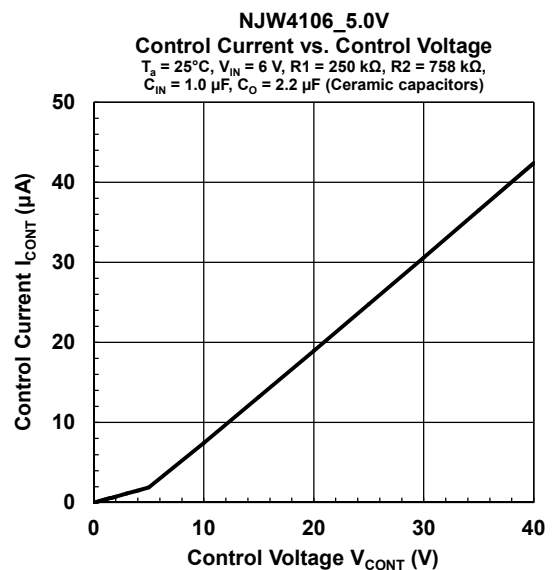
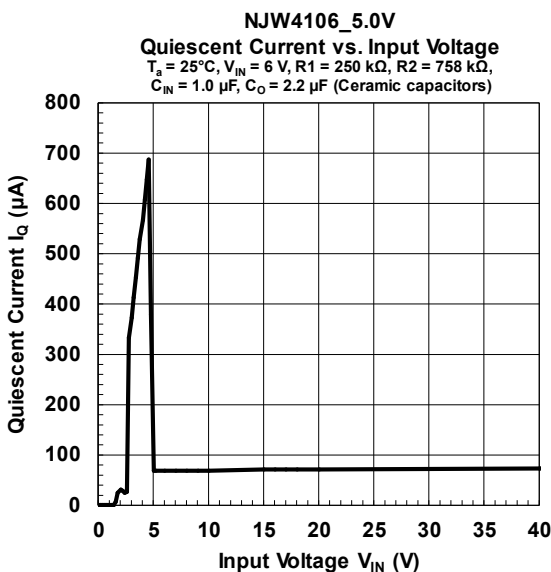
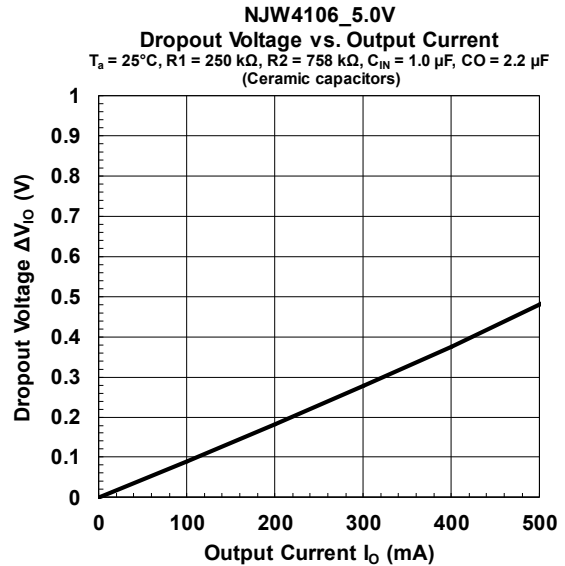
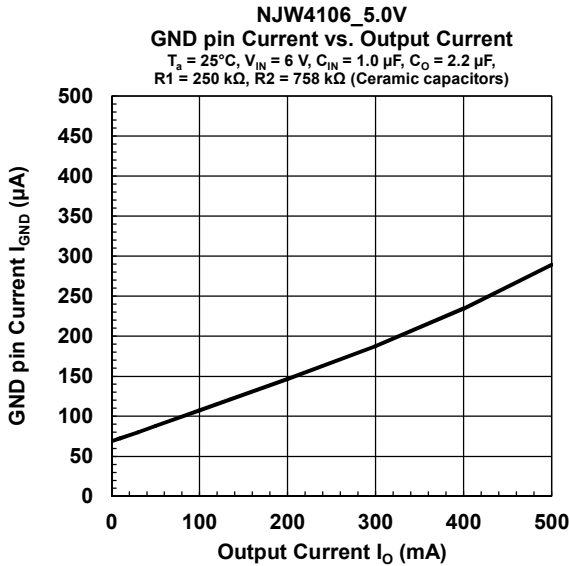
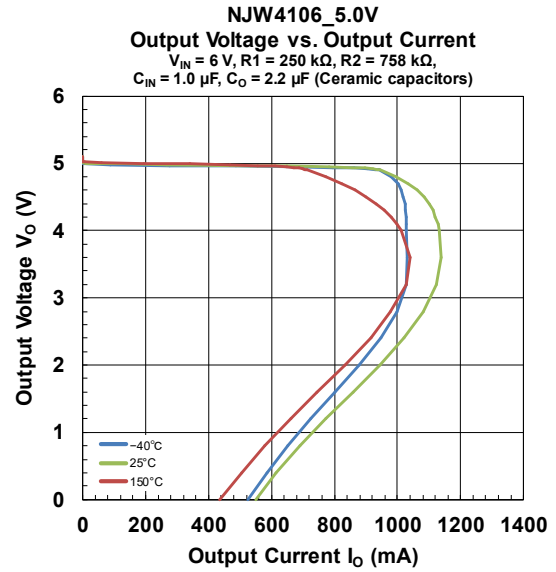
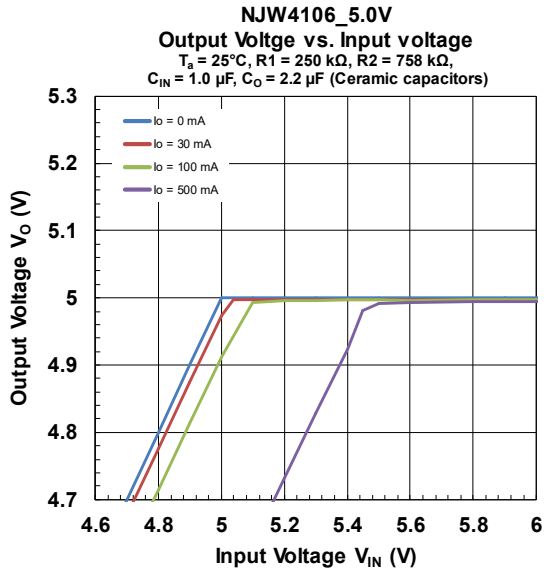
(6) 4-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 4-layer FR-4).

(For 4-layer: Applying 74.2 mm × 74.2 mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5.)

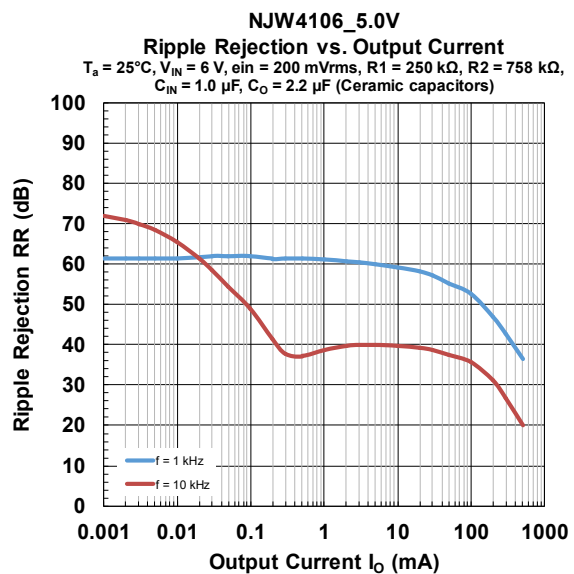
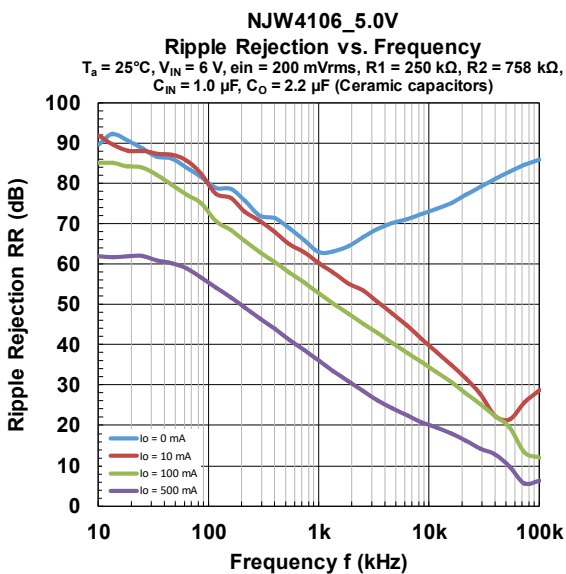
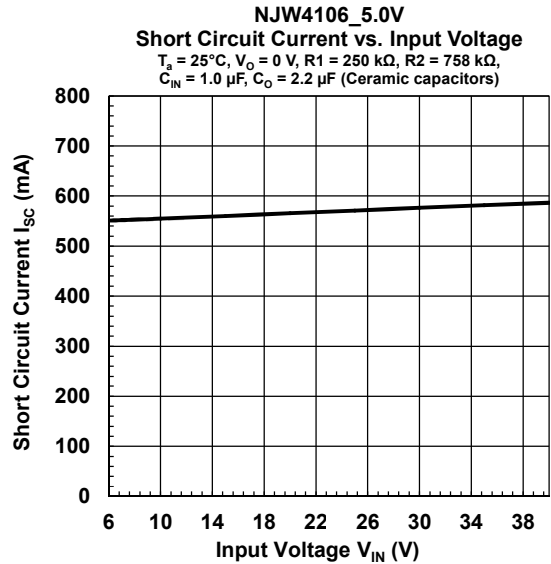
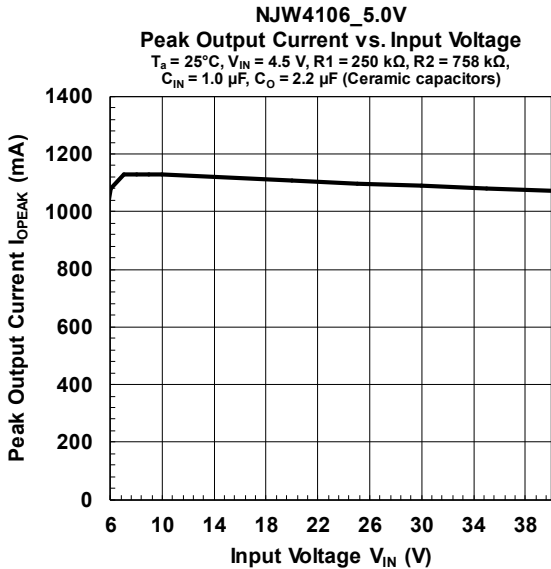
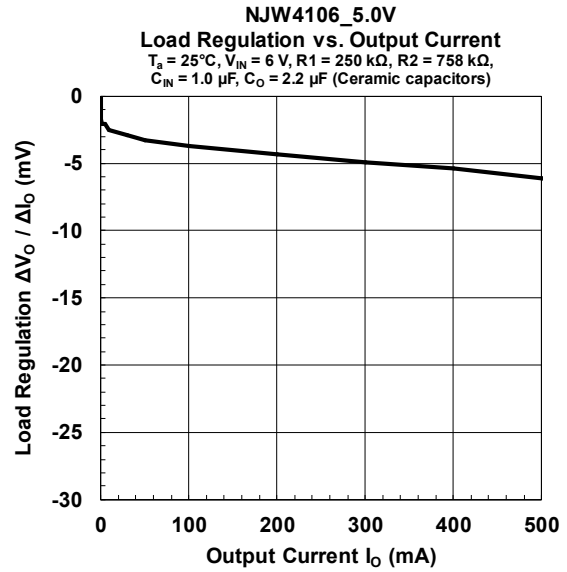
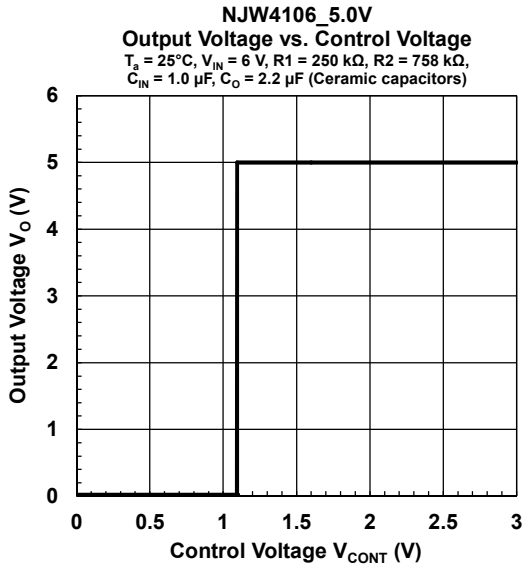
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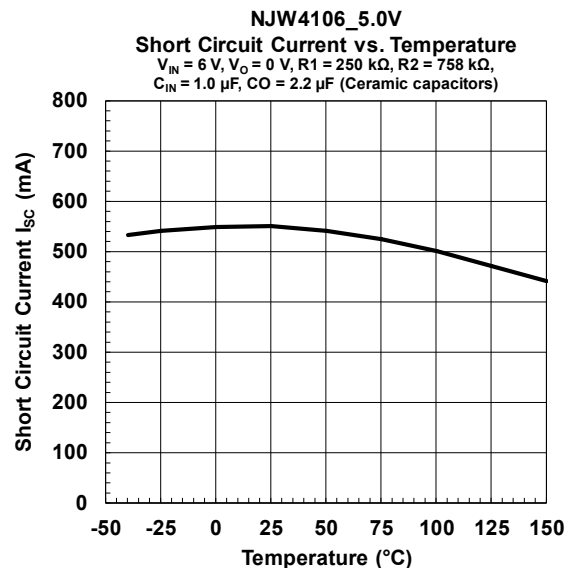
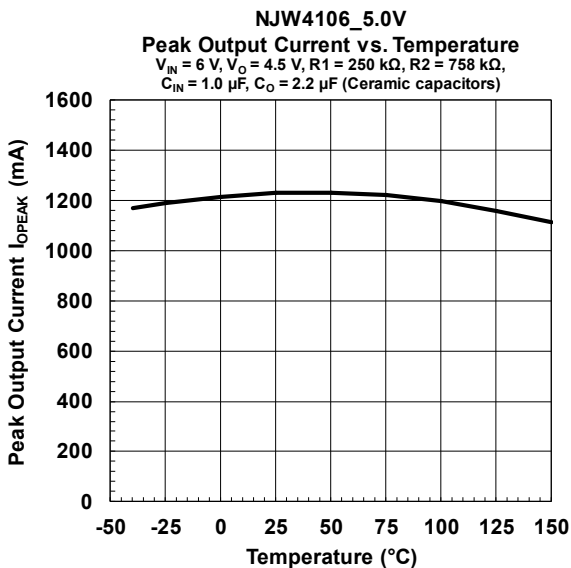
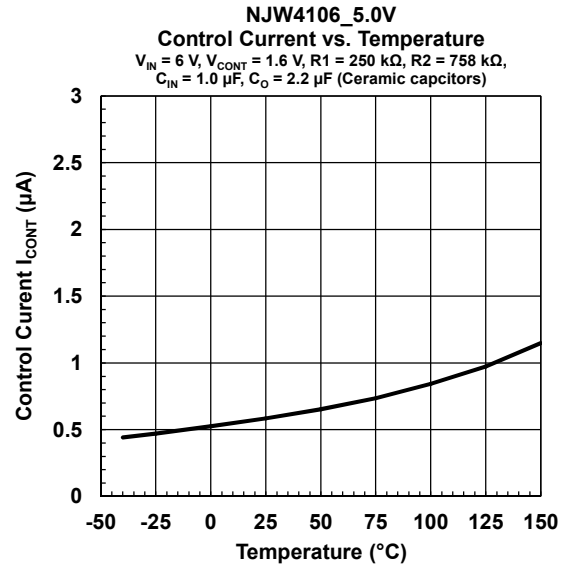
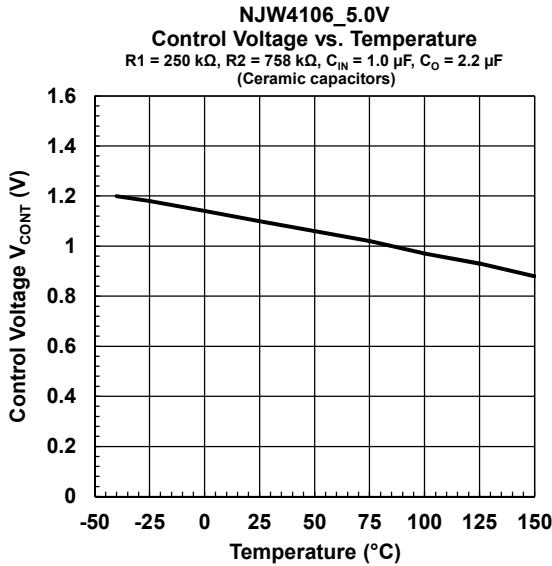
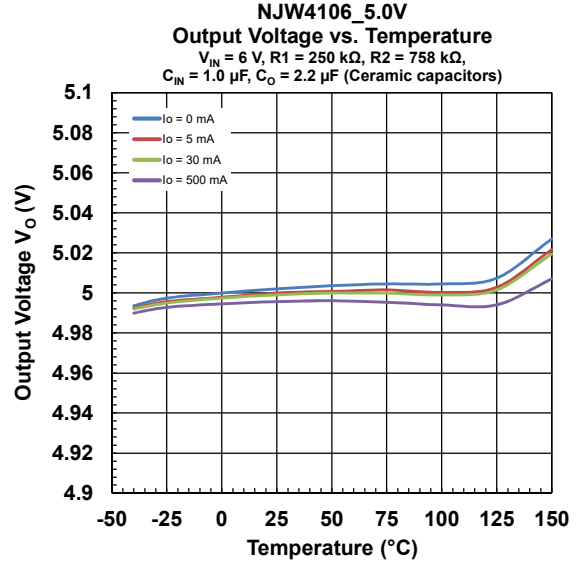
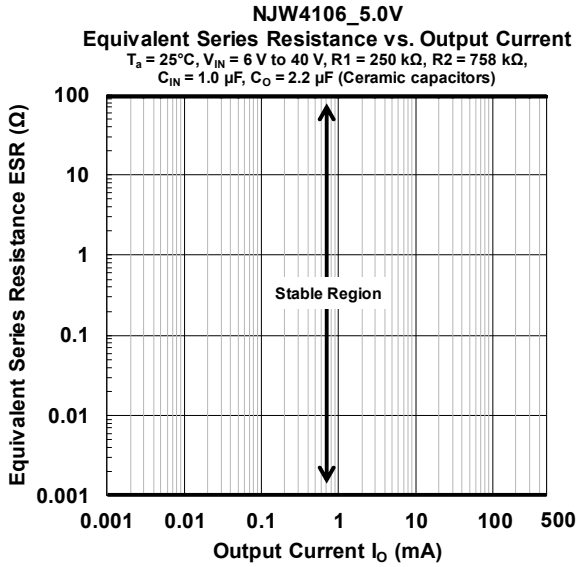
■ TYPICAL CHARACTERISTICS



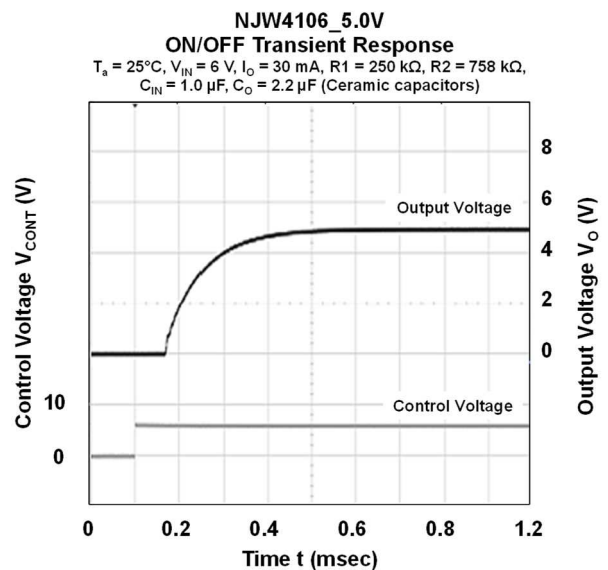
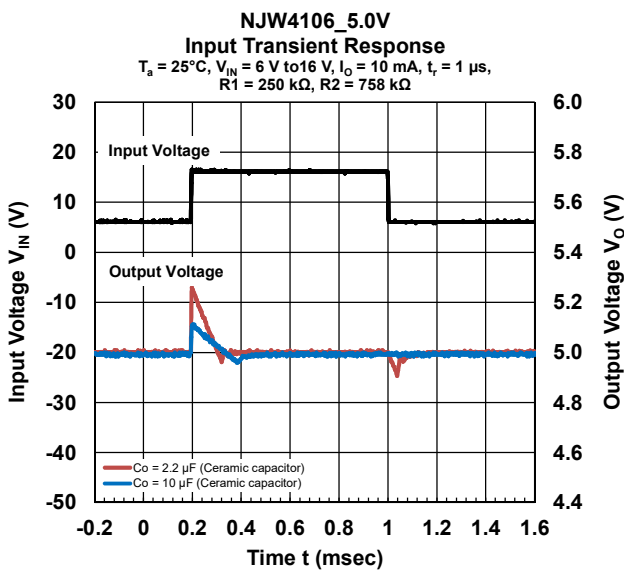
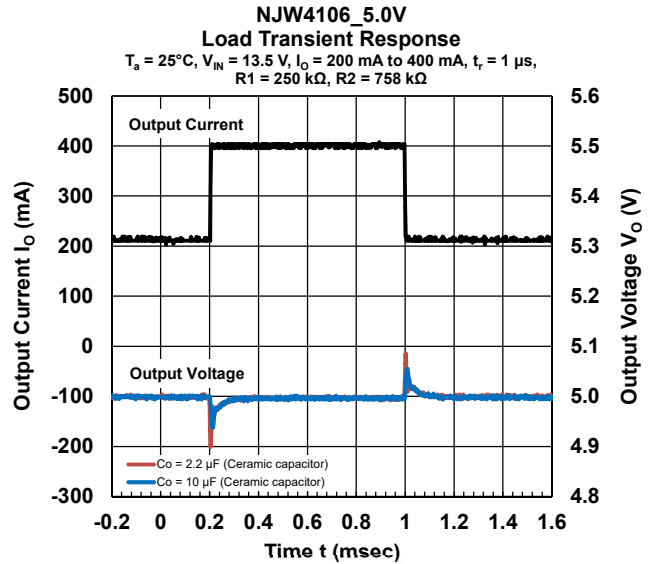
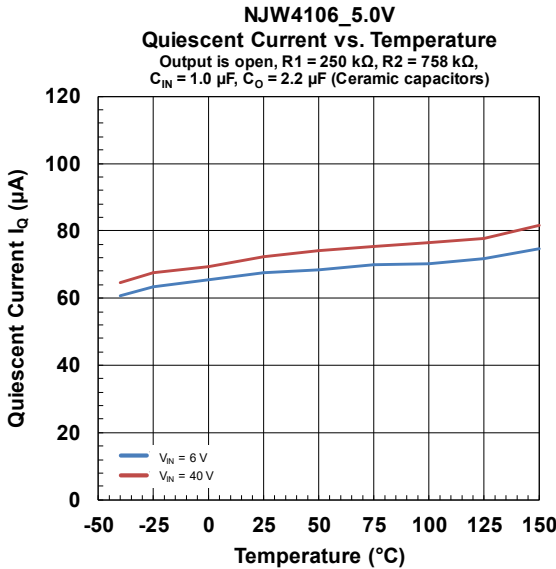
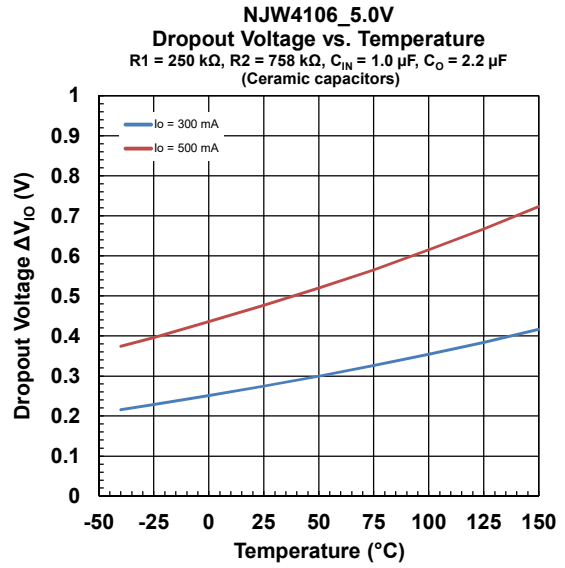
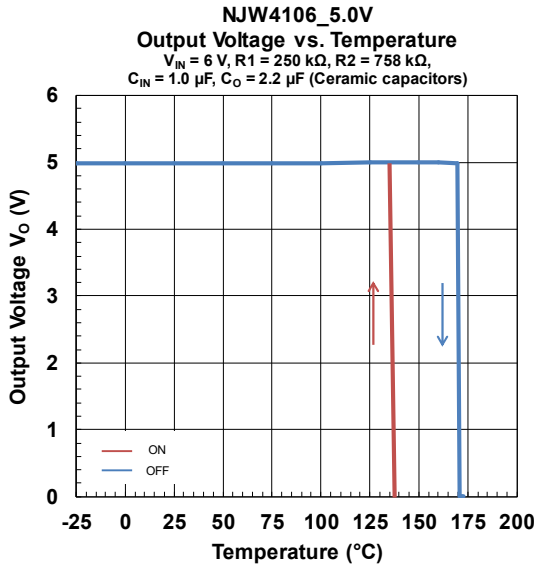
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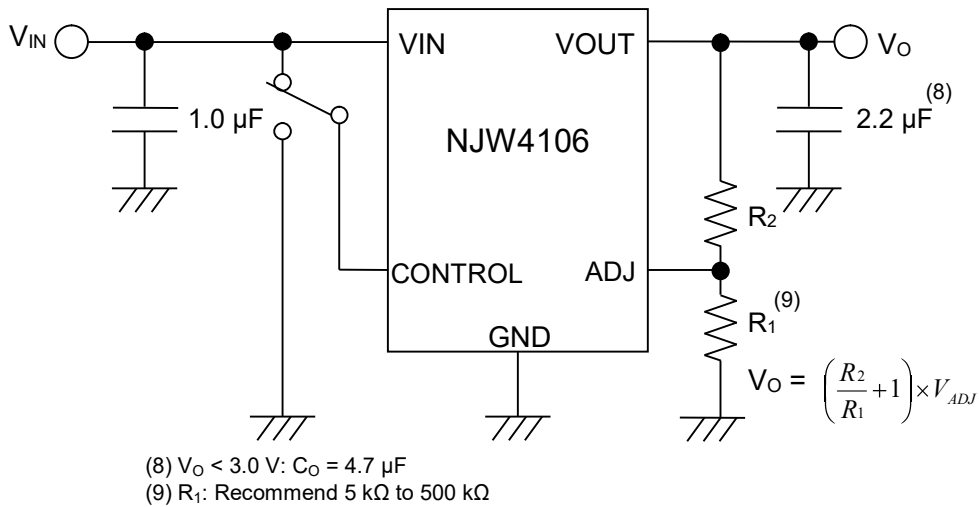


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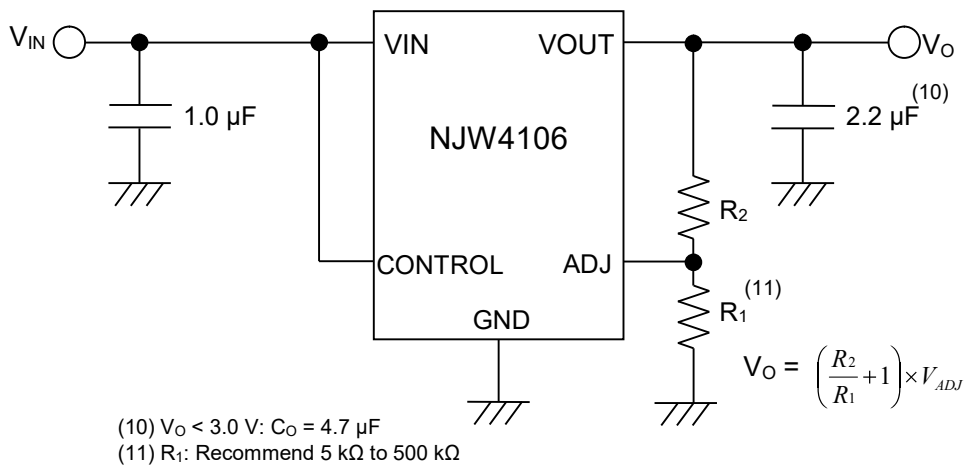
■ TYPICAL APPLICATION

1. When ON/OFF control is used.



The CONTROL pin is turned on at high level and turned off at open or low level.

2. When ON/OFF control is not used.



Connect the CONTROL pin to the V_{IN} .

■ APPLICATION NOTE

Input Capacitor (C_{IN})

The C_{IN} prevents oscillations and reduce power supply ripple of applications when the power supply impedance is high or power supply line is long. Connecting a 1.0 μ F or larger C_{IN} between V_{IN} and GND pins as short path as possible.

Output Capacitor (C_O)

C_O is necessary for phase compensation of the internal error amplifier in the regulator, and the capacitance value and ESR affect the stability of the circuit. If a capacitor less than 2.2 μ F (at $V_O \geq 3$ V) is used, output noise and/or regulator oscillation may occur due to lack of the phase compensation. For stable operation, connect a 2.2 μ F or larger C_O within the stable operation region ($0.001 \Omega \leq ESR \leq 100 \Omega$) between the V_{OUT} and GND pins as short path as possible. The recommended capacitance value varies depending on the output voltage, and a low output voltage may require a large capacitance value; therefore, confirm the recommended capacitance of the required output voltage. As the capacitance value of C_O increases, output noise and ripple decrease, and the response to output load fluctuations also improves.

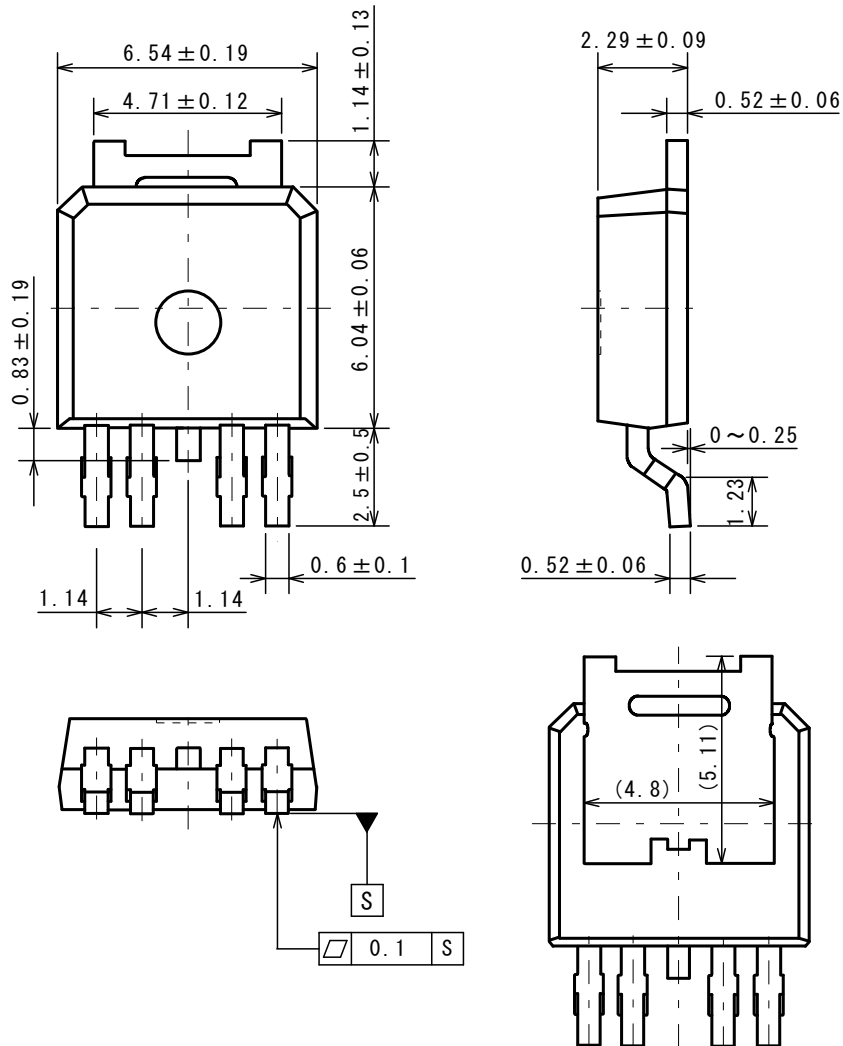
Select the output capacitor considering various characteristics such as frequency characteristics, temperature characteristics, and DC bias characteristics. For the C_O , a capacitor with excellent temperature characteristics and sufficient margin for output voltage is recommended.

Undervoltage Lockout (UVLO)

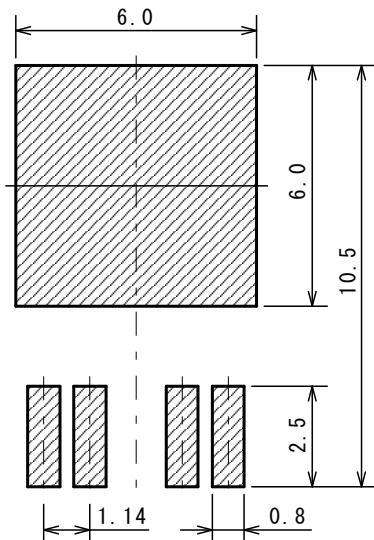
This circuit prevents malfunction by locking out the output when V_{IN} is below the UVLO detection voltage. The output voltage rises when the input voltage rises and exceeds the UVLO release voltage (2.7 V, typ). When the input voltage drops below the UVLO detection voltage (2.2 V, typ)*, the output voltage falls.

*UVLO detection voltage (2.2 V, typ) = UVLO release voltage (2.7 V, typ) – UVLO hysteresis voltage (500 mV, typ)

■ PACKAGE DIMENSIONS

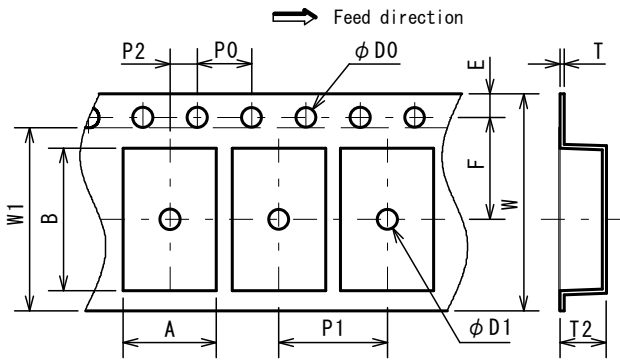


■ EXAMPLE OF SOLDER PADS DIMENSIONS



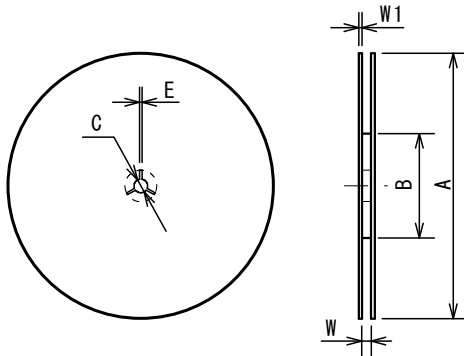
PACKING SPEC

TAPING DIMENSIONS



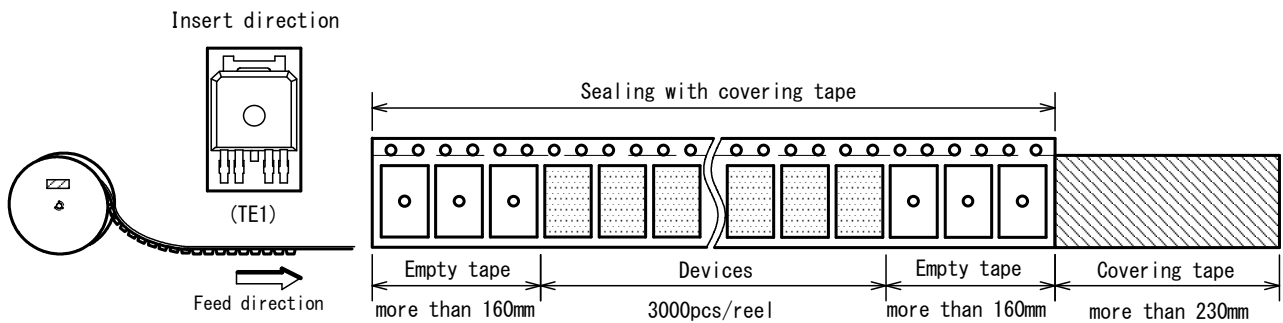
| SYMBOL | DIMENSION | REMARKS |
|--------|----------------------------------|------------------|
| A | 6.9±0.1 | BOTTOM DIMENSION |
| B | 10.5±0.1 | BOTTOM DIMENSION |
| D0 | 1.5 ^{+0.1} ₀ | |
| D1 | 1.5 ^{+0.1} ₀ | |
| E | 1.75±0.1 | |
| F | 7.5±0.1 | |
| P0 | 4.0±0.1 | |
| P1 | 8.0±0.1 | |
| P2 | 2.0±0.1 | |
| T | 0.3±0.1 | |
| T2 | 3.4 max | |
| W | 16.0±0.3 | |
| W1 | 13.5 | THICKNESS 0.1max |

REEL DIMENSIONS

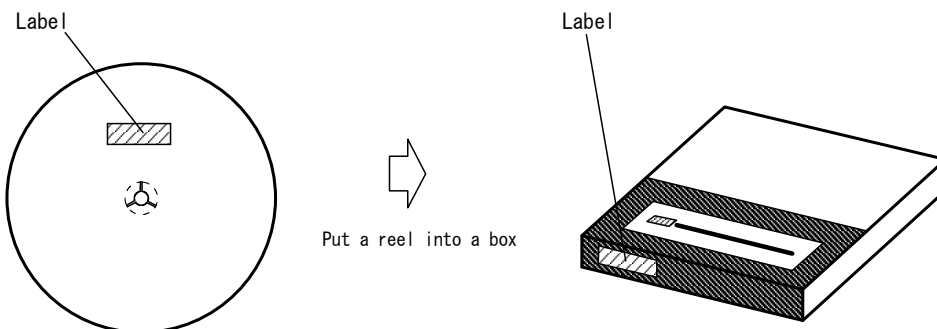


| SYMBOL | DIMENSION |
|--------|-----------|
| A | φ 330±2 |
| B | φ 80±1 |
| C | φ 13±0.5 |
| E | 2 |
| W | 17.5±0.5 |
| W1 | 2±0.5 |

TAPING STATE

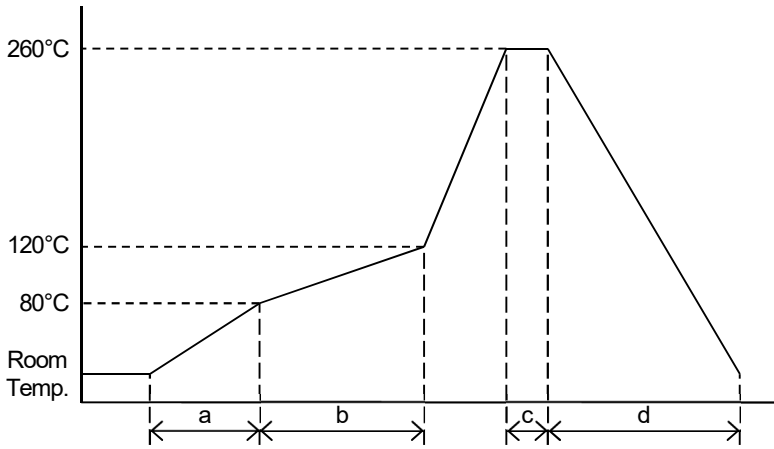


PACKING STATE



RECOMMENDED MOUNTING METHOD

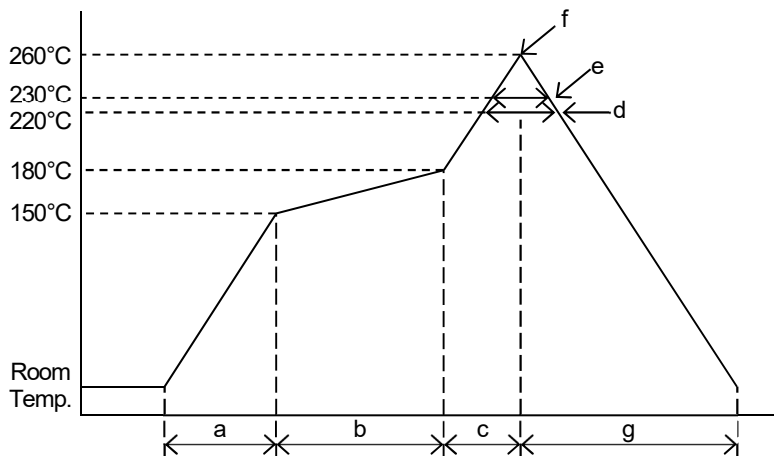
FLOW SOLDERING PROFILE



| | | |
|---|--------------------------|------------------|
| a | Temperature ramping rate | 1 to 7°C/s |
| b | Pre-heating temperature | 80 to 120°C |
| | Pre-heating time | 60 to 120s |
| c | Peak temperature | lower than 260°C |
| | Peak time | shorter than 10s |
| d | Temperature ramping rate | 1 to 7°C/s |

The temperature indicates at the surface of mold package.

INFRARED REFLOW SOLDERING PROFILE



| | | |
|---|--------------------------|------------------|
| a | Temperature ramping rate | 1 to 4°C/s |
| b | Pre-heating temperature | 150 to 180°C |
| | Pre-heating time | 60 to 120s |
| c | Temperature ramp rate | 1 to 4°C/s |
| d | 220°C or higher time | shorter than 60s |
| e | 230°C or higher time | shorter than 40s |
| f | Peak temperature | lower than 260°C |
| g | Temperature ramping rate | 1 to 6°C/s |

The temperature indicates at the surface of mold package.

REVISION HISTORY

| DATE | REVISION | CHANGES |
|--------------|----------|-------------|
| June 9, 2021 | Ver.1.0 | New Release |
| | | |

[CAUTION]

1. NJR strives to produce reliable and high quality semiconductors. NJR's semiconductors are intended for specific applications and require proper maintenance and handling. To enhance the performance and service of NJR's semiconductors, the devices, machinery or equipment into which they are integrated should undergo preventative maintenance and inspection at regularly scheduled intervals. Failure to properly maintain equipment and machinery incorporating these products can result in catastrophic system failures
2. The specifications on this datasheet are only given for information without any guarantee as regards either mistakes or omissions. The application circuits in this datasheet are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial property rights.
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3. To ensure the highest levels of reliability, NJR products must always be properly handled.
The introduction of external contaminants (e.g. dust, oil or cosmetics) can result in failures of semiconductor products.
4. NJR offers a variety of semiconductor products intended for particular applications. It is important that you select the proper component for your intended application. You may contact NJR's Sale's Office if you are uncertain about the products listed in this datasheet.
5. Special care is required in designing devices, machinery or equipment which demand high levels of reliability. This is particularly important when designing critical components or systems whose failure can foreseeably result in situations that could adversely affect health or safety. In designing such critical devices, equipment or machinery, careful consideration should be given to amongst other things, their safety design, fail-safe design, back-up and redundancy systems, and diffusion design.
6. The products listed in this datasheet may not be appropriate for use in certain equipment where reliability is critical or where the products may be subjected to extreme conditions. You should consult our sales office before using the products in any of the following types of equipment.
 - Aerospace Equipment
 - Equipment Used in the Deep Sea
 - Power Generator Control Equipment (Nuclear, steam, hydraulic, etc.)
 - Life Maintenance Medical Equipment
 - Fire Alarms / Intruder Detectors
 - Vehicle Control Equipment (Airplane, railroad, ship, etc.)
 - Various Safety Devices
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8. Warning for handling Gallium and Arsenic (GaAs) Products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
9. The product specifications and descriptions listed in this datasheet are subject to change at any time, without notice.

